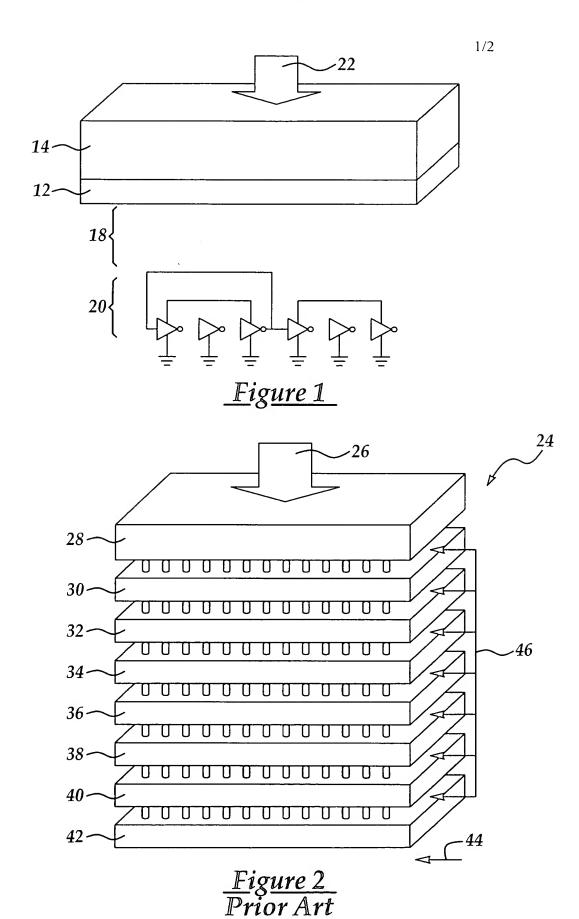
Inventor(s): Chou
Serial No.: To Be Assigned

Filed: Herewith

For: Single Layer Wiring Bond Pad With Optimum ... Under Pads

Attorney Docket No.: 67,200-603



Inventor(s): Chou
Serial No.: To Be Assigned
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64
66
Figure 3

